

### Discription

The HPESDNC5D5VB protects sensitive semiconductor components from damage or upset due to electrostatic discharge (ESD) and other voltage induced transient events. Excellent clamping capability, low leakage, low capacitance, and fast response time provide best in class protection on designs that are exposed to ESD. It gives designer the flexibility to protect one bi-directional

line in applications where arrays are not practical.

#### Features

- ★ Transient protection for high-speed data lines IEC 61000-4-2(ESD) ±30kV (Contact) ±30kV (Air)
- IEC 61000-4-4(EFT) 40A (5/50 ns) ★ Peak power dissipation: 400W (8/20us)
- ★ Working voltages : 5V
- ★ Protects one Vcc or data line
- ★ Low clamping voltage
- ★ Low leakage current

## **Orderingin formation**

SOD-523	



Product ID	Pack	Qty(PCS)
HPESDNC5D5VB	SOD-523	3000

## Absolute Ratings(Tamb = 25°C)

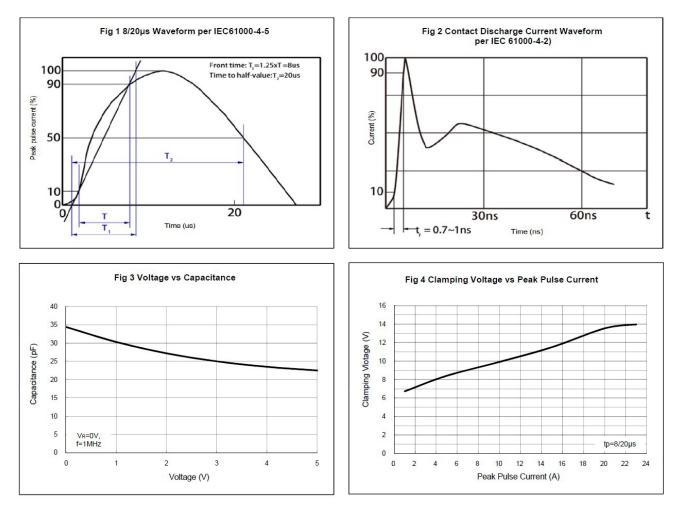
Symbol	Parameter	Value	Units	
P <sub>PP</sub>	Peak Pulse Power ( $t_p = 8/20 \ \mu \ s$ )	400	W	
TL	Maximum lead temperature for soldering during 10s	260	°C	
T <sub>stg</sub>	Storage Temperature Range	-55 to +155	°C	
T <sub>op</sub>	Operating Temperature Range		-40 to +125	°C
Tj	Maximum junction temperature		150	°C
	IEC61000-4-2 (ESD) air discha contact discha		±30 ±30	KV
	IEC61000-4-4 (EFT)		40	А



## **Electrical Characteristics**

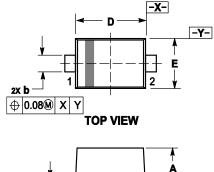
Symbol	Parameter	Test Condition Min		Тур	Max	Units
Vrwm	Reverse Working Voltage				5.0	V
Vbr	Reverse Breakdown Voltage	I⊤ = 1mA	5.8		7.8	V
IR	Reverse Leakage Current	$V_{\text{RWM}} = 5.0V$			1.0	μA
Vc	Clamping Voltage	$I_{RWM} = 1A, t_{P} = 8/20 \mu s$			9.8	V
		I <sub>RWM</sub> = 20Α, t <sub>p</sub> = 8/20μs		15	20	V
CJ	Junction Capacitance	$V_R = 0V$ , f = 1MHz		33	40	pF

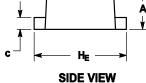
# **Typical Characteristics**

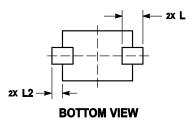




## **Outline And Dimensions**







Notes:

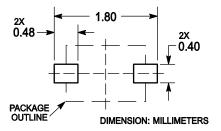
- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMETERS.

3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.50	0.60	0.70	0.020	0.024	0.028
b	0.25	0.30	0.35	0.010	0.012	0.014
С	0.07	0.14	0.20	0.003	0.006	0.008
D	1.10	1.20	1.30	0.043	0.047	0.051
Е	0.70	0.80	0.90	0.028	0.031	0.035
H <sub>E</sub>	1.50	1.60	1.70	0.059	0.063	0.067
L	0.30 REF			0.012 REF		
L <sub>2</sub>	0.15	0.20	0.25	0.006	0.008	0.010

# **Soledering Footprint**





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